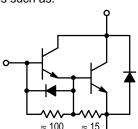
Designer's™ Data Sheet

SWITCHMODE Series NPN Silicon Power Darlington Transistors with Base-Emitter Speedup Diode

The MJ10022 and MJ10023 Darlington transistors are designed for high–voltage, high–speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line–operated switchmode applications such as:

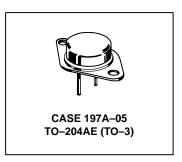
- AC and DC Motor Controls
- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Fast Turn-Off Times
 - 150 ns Inductive Fall Time @ 25°C (Typ) 300 ns Inductive Storage Time @ 25°C (Typ)
- Operating Temperature Range 65 to + 200°C
- 100°C Performance Specified for:

Reversed Biased SOA with Inductive Loads Switching Times with Inductive Loads Saturation Voltages Leakage Currents



MJ10022 MJ10023

40 AMPERE
NPN SILICON
POWER DARLINGTON
TRANSISTORS
350 AND 400 VOLTS
250 WATTS



MAXIMUM RATINGS

Rating	Symbol	MJ10022	MJ10023	Unit
Collector–Emitter Voltage	VCEO	350	400	Vdc
Collector–Emitter Voltage	VCEV	450	600	Vdc
Emitter Base Voltage	V _{EB}	80		Vdc
Collector Current — Continuous — Peak (1)	I _C	40 80		Adc
Base Current — Continuous — Peak (1)	I _B	20 40		Adc
Total Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$ Derate above 25°C	PD	250 143 1.43		Watts W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-65 to +200		°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{ heta JC}$	0.7	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	TL	275	°C

⁽¹⁾ Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

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Designer's Data for "Worst Case" Conditions — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.



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ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS		•			•		•
Collector–Emitter Sustain (I _C = 100 mA, I _B = 0)		ИJ10022 ИJ10023	VCEO(sus)	350 400	_	_	Vdc
Collector Cutoff Current (VCEV = Rated Value, VBE(off) = 1.5 Vdc) (VCEV = Rated Value, VBE(off) = 1.5 Vdc, TC = 150°C)			ICEV	_	_ _	0.25 5.0	mAdc
Collector Cutoff Current (V _{CE} = Rated V _{CEV} , R	R _{BE} = 50 Ω, T _C = 100°C)		ICER	_	_	5.0	mAdc
Emitter Cutoff Current (VEB = 2.0 V, IC = O)			I _{EBO}	_	_	175	mAdc
SECOND BREAKDOWN							
Second Breakdown Colle	ctor Current with Base Forward Biased		I _{S/b}		See Figure 13		
Clamped Inductive SOA	with Base Reverse Biased		RBSOA		See Figure 14		
ON CHARACTERISTICS (1)						
DC Current Gain (I _C = 10 Adc, V _{CE} = 5.	0 V)		hFE	50	_	600	_
Collector–Emitter Saturation Voltage (I_C = 20 Adc, I_B = 1.0 Adc) (I_C = 40 Adc, I_B = 5.0 Adc) (I_C = 20 Adc, I_B = 10 Adc, I_C = 100°C)		VCE(sat)	_ _ _	_ _ _	2.2 5.0 2.5	Vdc	
Base–Emitter Saturation Voltage ($I_C = 20$ Adc, $I_B = 1.2$ Adc) ($I_C = 20$ Adc, $I_B = 1.2$ Adc, $T_C = 100$ °C)		VBE(sat)		_ _	2.5 2.5	Vdc	
Diode Forward Voltage (IF = 20 Adc)			V _f	_	2.5	5.0	Vdc
DYNAMIC CHARACTERIS	STICS					l	1
Output Capacitance (VCB = 10 Vdc, IE = 0, f _{test} = 1.0 kHz)		C _{ob}	150	_	600	pF	
SWITCHING CHARACTER	RISTICS	•				•	
Resistive Load (Table 1))						
Delay Time			^t d	_	0.03	0.2	μs
Rise Time	$(V_{CC} = 250 \text{ Vdc}, I_{C} = 20 \text{ A}, I_{B1} = 1.0 \text{ Vpc}$	Adc,	t _r	_	0.4	1.2	μs
Storage Time	$V_{BE(off)} = 5.0 \text{ V, t}_{p} = 50 \mu\text{s},$ Duty Cycle $\leq 2.0\%$)		t _S	_	0.9	2.5	μs
Fall Time			t _f		0.3	0.9	μs
Inductive Load, Clampe	ed (Table 1)						
Storage Time	$(I_{CM} = 20 \text{ A}, V_{CEM} = 250 \text{ V}, I_{B1} = 1.0 \text{ A}, V_{BE(off)} = 5 \text{ V}, T_{C} = 100^{\circ}\text{C})$		t _{SV}	_	1.9	4.4	μs
Crossover Time			t _C		0.6	2.0	μs
Fall Time			^t fi	_	0.3	_	μs
Storage Time	(I _{CM} = 20 A, V _{CEM} = 250 V, I _{B1} = 1.0 A, V _{BE(off)} = 5 V, T _C = 25°C)		t _{SV}	_	1.0	_	μs
Crossover Time			t _C	_	0.3	_	μs
Fall Time			t _{fi}	_	0.15	_	μs

⁽¹⁾ Pulse Test: PW = 300 µs, Duty Cycle ≤ 2%.

TYPICAL ELECTRICAL CHARACTERISTICS

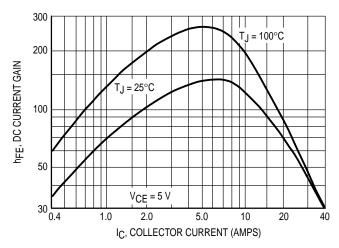


Figure 1. DC Current Gain

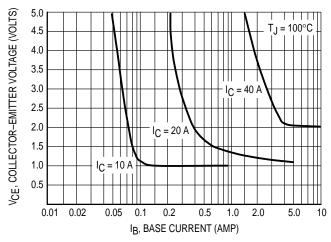


Figure 2. Collector Saturation Region

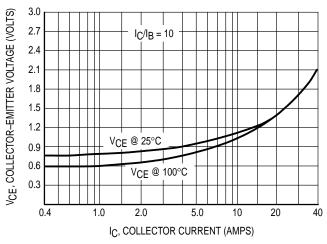


Figure 3. Collector-Emitter Saturation Voltage

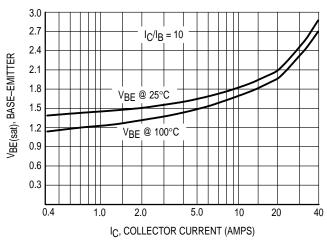


Figure 4. Base-Emitter Saturation Voltage

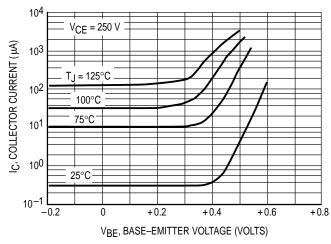


Figure 5. Collector Cutoff Region

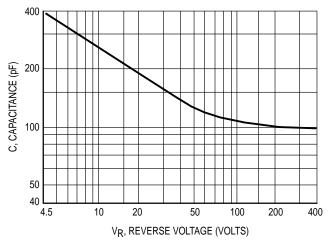
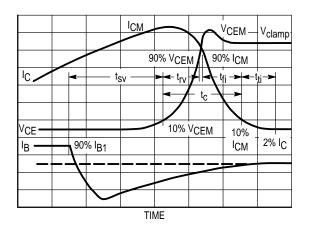


Figure 6. Cob, Output Capacitance

Table 1. Test Conditions for Dynamic Performance

	V _{CEO(sus)}	RBSOA AND INDUCTIVE SWITCHING	RESISTIVE SWITCHING	
INPUT CONDITIONS	$ \begin{array}{c c} 20 \Omega \\ \hline 0 & 1 \end{array} $ $ \begin{array}{c c} 5 V \\ \hline 0 & 2 \end{array} $ PW Varied to Attain $ \begin{array}{c c} I_C = 100 \text{ mA} \end{array} $	INDUCTIVE TEST CIRCUIT TUT IN4937 OR SEE ABOVE FOR DETAILED CONDITIONS 2 RS = 0.1 \(\Omega \)	TURN-ON TIME O 1 IB1 = 0 2 IB1 adjusted to obtain the forced hFE desired TURN-OFF TIME Use inductive switching driver as the input to the resistive test circuit.	
CIRCUIT	$L_{coil} = 10 \text{ mH}, V_{CC} = 10 \text{ V}$ $R_{coil} = 0.7 \Omega$ $V_{clamp} = V_{CEO(sus)}$	L_{COII} = 180 μH R_{COII} = 0.05 Ω V_{CC} = 20 V	V_{CC} = 250 V R_L = 12.5 Ω Pulse Width = 25 μ s	
TEST CIRCUITS	1	OUTPUT WAVEFORMS $t_{1} \text{ Adjusted to} \\ \text{Obtain } I_{C} \\ t_{1} \approx \frac{L_{coil} \text{ (ICM)}}{V_{CC}} \\ t_{2} \approx \frac{L_{coil} \text{ (ICM)}}{V_{clamp}} \\ \text{Test Equipment} \\ \text{Scope} - \text{Tektronix} \\ 475 \text{ or Equivalent} \\ \end{cases}$	RESISTIVE TEST CIRCUIT TUT Rel Rel Rel Rel Rel Rel Rel Re	



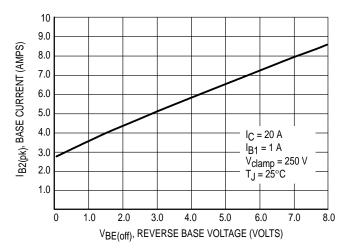


Figure 7. Inductive Switching Measurements

Figure 8. Typical Peak Reverse Base Current

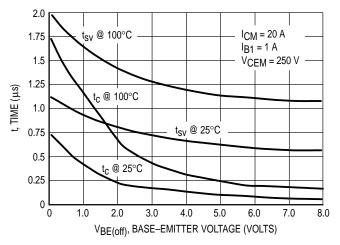


Figure 9. Typical Inductive Switching Times

SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

t_{SV} = Voltage Storage Time, 90% I_{B1} to 10% V_{CEM}

 t_{rv} = Voltage Rise Time, 10-90% V_{CEM}

tfi = Current Fall Time, 90-10% ICM

tti = Current Tail, 10-2% ICM

 t_C = Crossover Time, 10% V_{CEM} to 10% I_{CM}

An enlarged portion of the inductive switching waveform is

shown in Figure 7 to aid on the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN–222A:

$$PSWT = 1/2 VCCIC(t_C)f$$

In general, $t_{\Gamma V} + t_{fi} \cong t_C$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user orinented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_{C} and t_{SV}) which are guaranteed at 100°C .

RESISTIVE SWITCHING

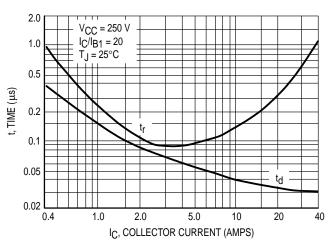


Figure 10. Typical Turn-On Switching Times

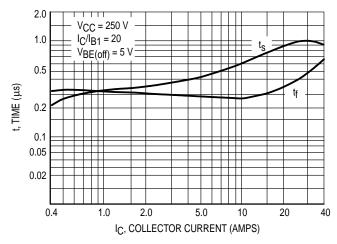


Figure 11. Typical Turn-Off Switching Times

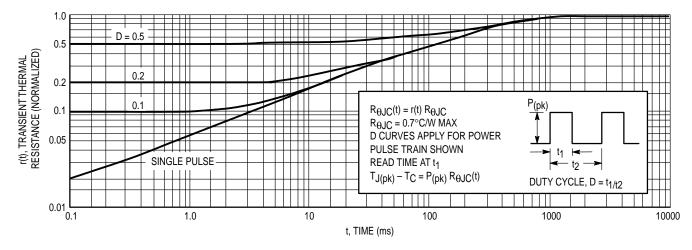


Figure 12. Thermal Response

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The Safe Operating Area figures shown in Figures 13 and 14 are specified for these devices under the test conditions shown.

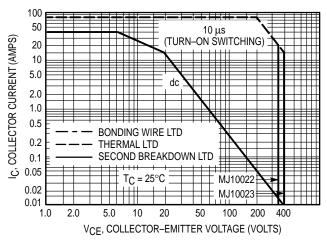


Figure 13. Maximum Forward Bias Safe Operating Area

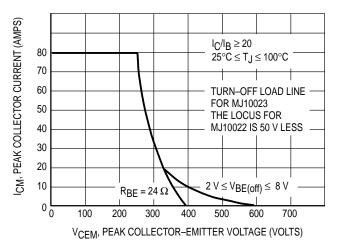


Figure 14. Maximum RBSOA, Reverse Bias Safe Operating Area

SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate IC – VCE limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 13 is based on $T_C = 25\,^{\circ}C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25\,^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 13 may be found at any case temperature by using the appropriate curve on Figure 15.

 $T_{J(pk)}$ may be calculated from the data in Figure 12. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn—off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage—current condition allowable during reverse biased turn—off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 14 gives the RBSOA characteristics.

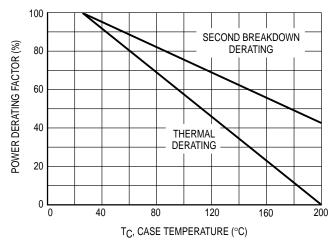
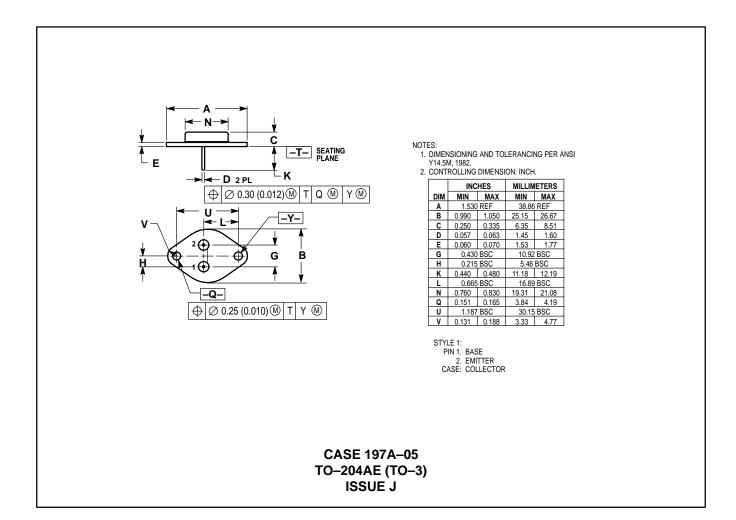


Figure 15. Power Derating

PACKAGE DIMENSIONS



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